



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 4981
Hiroshi TAKANASHI et al. : Docket No. 2000_1749
Serial No. 09/739,750 : Group Art Unit 1752
Filed December 20, 2000 : Examiner S. Lee

NEGATIVE-WORKING PHOTOSENSITIVE :
RESIN COMPOSITION AND PHOTO-
SENSITIVE RESIN PLATE USING THE
SAME

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEE FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975.

RESPONSE

Assistant Commissioner for Patents,
Washington, D.C.

Sir:

In response to the Official Action of December 7, 2001, please amend the present application as follows:

IN THE SPECIFICATION:

Please rewrite paragraph [0056] as follows:

[0056] EXAMPLES 1 - 17:

(i) Preparation of water-soluble photosensitive resin compositions 1-17:

In 200 parts by weight of water was dissolved 200 parts by weight of polyvinyl alcohol (degree of saponification: 70%, degree of polymerization: 500) as component (A), and then 70 parts by weight of polyethylene glycol diacrylate as component (B), 4 parts by weight of benzylidemethyl ketal as component (C), 0.1 part by weight of methylhydroquinone as component (D), and X wt. % based on the weight of the photosensitive composition (X: addition amount indicated in Table I below) of p-toluenesulfonamide were added as component (E) to the solution



5/A
J